

[Committee Print]

[SHOWING THE TEXT OF H.R. 6207, AS FORWARDED BY THE COMMERCE
MANUFACTURING, AND TRADE SUBCOMMITTEE OF ENERGY AND COM-
MERCE ON SEPTEMBER 1, 2026]

119TH CONGRESS
2D SESSION

H. R. 6207

To prohibit purchases of certain semiconductor manufacturing equipment
from foreign entities of concern or subsidiaries of foreign entities of
concern, and for other purposes.

IN THE HOUSE OF REPRESENTATIVES

NOVEMBER 20, 2025

Ms. LOFGREN (for herself, Mr. OBERNOLTE, Mr. KRISHNAMOORTHY, Mr.
MOOLENAAR, Mr. LANDSMAN, and Mrs. HOUCHIN) introduced the fol-
lowing bill; which was referred to the Committee on Energy and Com-
merce, and in addition to the Committee on Science, Space, and Tech-
nology, for a period to be subsequently determined by the Speaker, in
each case for consideration of such provisions as fall within the jurisdic-
tion of the committee concerned

A BILL

To prohibit purchases of certain semiconductor manufac-
turing equipment from foreign entities of concern or
subsidiaries of foreign entities of concern, and for other
purposes.

1 *Be it enacted by the Senate and House of Representa-*
2 *tives of the United States of America in Congress assembled,*

1 **SECTION 1. SHORT TITLE.**

2 This Act may be cited as the “Chip Equipment Qual-
3 ity, Usefulness, and Integrity Protection Act of 2026” or
4 the “Chip EQUIP Act”.

5 **SEC. 2. PURCHASES OF SEMICONDUCTOR MANUFAC-**
6 **TURING EQUIPMENT.**

7 (a) DEFINITIONS.—Section 9901 of the William M.
8 (Mac) Thornberry National Defense Authorization Act for
9 Fiscal Year 2021 (15 U.S.C. 4651) is amended by adding
10 at the end the following:

11 “(14) The term ‘completed, fully assembled’,
12 with respect to semiconductor manufacturing equip-
13 ment, means the state in which all (or substantially
14 all) necessary parts, chambers, subsystems, and sub-
15 components have been put together, resulting in
16 such equipment that is—

17 “(A) ready-to-use or ready-to-install; and

18 “(B) ready to be purchased directly from
19 an entity.

20 “(15) The term ‘ineligible semiconductor manu-
21 facturing equipment’—

22 “(A) means completed, fully assembled
23 equipment that is manufactured, assembled, or
24 refurbished by a foreign entity of concern, or a
25 subsidiary or affiliate thereof, and designed for
26 use in the fabrication, assembly, testing, ad-

1 vanced packaging, production, or research and
2 development of semiconductors;

3 “(B) includes—

4 “(i) deposition equipment;

5 “(ii) etching equipment;

6 “(iii) lithography equipment;

7 “(iv) inspection, measuring, and test
8 equipment;

9 “(v) wafer slicing equipment;

10 “(vi) wafer dicing equipment;

11 “(vii) wire bonders;

12 “(viii) ion implantation equipment;

13 “(ix) chemical mechanical polishing;

14 “(x) diffusion or oxidation furnaces;

15 “(xi) thermal processing equipment;

16 and

17 “(xii) automated material handling
18 systems; and

19 “(C) does not include any part, chamber,
20 subsystem, or subcomponent that enables or is
21 incorporated into such equipment.”.

22 (b) INELIGIBLE USE OF FUNDS.—Section 9909 of
23 the William M. (Mac) Thornberry National Defense Au-
24 thorization Act for Fiscal Year 2021 (15 U.S.C. 4659)
25 is amended—

1 (1) by redesignating subsection (f) as sub-
2 section (g); and

3 (2) by inserting after subsection (e) the fol-
4 lowing new subsection:

5 “(f) INELIGIBLE USE OF FUNDS.—

6 “(1) IN GENERAL.—Subject to paragraphs (2)
7 and (3), the Secretary shall include in the terms of
8 each agreement with a covered entity for the award
9 of Federal financial assistance under section 9902,
10 or with the recipient of an award made under sec-
11 tion 9906, prohibitions with respect to a project re-
12 lating to the procurement, installation, or use of in-
13 eligible semiconductor manufacturing equipment, to
14 be effective for 10 years beginning on the date on
15 which the agreement is signed.

16 “(2) WAIVER.—The Secretary may waive the
17 prohibitions referred to in paragraph (1) if—

18 “(A) the ineligible semiconductor manufac-
19 turing equipment to be purchased by the appli-
20 cable covered entity is not produced in the
21 United States or an allied or partner country in
22 sufficient and reasonably available quantities or
23 of a satisfactory quality to support established
24 or expected production capabilities;

1 “(B) the ineligible semiconductor manufac-
2 turing equipment at issue was manufactured or
3 assembled by an entity that is not a foreign en-
4 tity of concern, or a subsidiary or affiliate
5 thereof, and was refurbished by a foreign entity
6 of concern ,or a subsidiary or affiliate thereof;
7 or

8 “(C)(i) the use of the ineligible semicon-
9 ductor manufacturing equipment complies with
10 the requirements set forth in the Export Ad-
11 ministration Regulations (as such term is de-
12 fined in section 1742 of the Export Control Re-
13 form Act of 2018 (50 U.S.C. 4801)); and

14 “(ii) the Secretary, in consultation
15 with the Director of National Intelligence
16 or the Secretary of Defense, determines
17 such waiver is in the national security in-
18 terest of the United States.

19 “(3) PRIOR AGREEMENTS.—

20 “(A) IN GENERAL.—The prohibitions re-
21 ferred to in paragraph (1) shall not apply to
22 any ineligible semiconductor manufacturing
23 equipment that—

1 “(i) has been installed by the applica-
2 ble covered entity prior to the date of en-
3 actment of the Chip EQUIP Act; or

4 “(ii) is allowed to be procured, in-
5 stalled, or used by the applicable covered
6 entity under the terms of an agreement
7 that was entered into before the date of
8 enactment of the Chip EQUIP Act be-
9 tween the Secretary and the covered entity.

10 “(B) LIMITATION.—Nothing in clause (ii)
11 of subparagraph (A) shall be construed to au-
12 thorize the procurement, installation, or use of
13 ineligible semiconductor manufacturing equip-
14 ment that is not allowed under the terms of an
15 agreement entered into prior to the date of en-
16 actment of the Chip EQUIP Act.

17 “(4) FOREIGN ENTITIES OF CONCERN.—Noth-
18 ing in this subsection may be construed to waive the
19 application of section 9907.”.